

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Bong-hyup Kang</td> <td>01/28/2009</td> </tr> <tr> <td>Chang-won Jeon</td> <td>01/28/2009</td> </tr> <tr> <td>Han-seok Ko</td> <td>01/28/2009</td> </tr> </tbody> </table>		Name	Execution Date	Bong-hyup Kang	01/28/2009	Chang-won Jeon	01/28/2009	Han-seok Ko	01/28/2009		
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CORRESPONDENCE DATA											
Fax Number:	(312)569-3533										
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ATTORNEY DOCKET NUMBER:	P3059US
NAME OF SUBMITTER:	Mark Bergner
Total Attachments: 2 source=P3059US_Assignment#page1.tif source=P3059US_Assignment#page2.tif	

Drinker Biddle & Reath LLP
191 N. Wacker Drive, Suite 3700
Chicago, Illinois 60606-1698

ASSIGNMENT

WHEREAS, WE, Bong-hyup KANG, of c/o Samsung Techwin Co., Ltd., 28 Sungju-dong, Changwon-city, Kyongsangnam-do, Republic of Korea, Chang-won JEON, of 2110 CJ Village, Anyang 6-dong, Manan-gu, Anyang-si, Gyeonggi-do, Republic of Korea, and Han-seok KO, of 16-703 Shindonga Apt., Seobinggo-dong, Yongsan-gu, Seoul, Republic of Korea, have invented and own a certain invention entitled:

**PRE-PROCESSING METHOD AND APPARATUS FOR WIDE
DYNAMIC RANGE IMAGE PROCESSING**

for which invention we have executed an application (provisional or non-provisional) for a U.S. patent, which was filed on 03/18/2009, under U.S. Application No. 12/381,920, and

WHEREAS, SAMSUNG TECHWIN CO., LTD., of 28 Sungju-dong, Changwon-city, Kyongsangnam-do, Republic of Korea, and **KOREA UNIVERSITY INDUSTRIAL & ACADEMIC COLLABORATION FOUNDATION**, of Korea University, 1 Anamdong 5-ga, Seongbuk-gu, Seoul 136-701, Republic of Korea (hereinafter referred to as Assignees), are desirous of acquiring the entire domestic and foreign right, title, and interest in and under the invention described in the patent application.

NOW, THEREFORE, for good and valuable considerations, the receipt and sufficiency of which are hereby acknowledged, we assign and transfer to the Assignees and the Assignees' legal representatives, successors and assigns the full and exclusive rights in and to the invention in the U.S. and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisionals, reissues, reexaminations, National phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and we do hereby authorize and request the Commissioner of Patents to issue U.S. patents to the above-mentioned Assignees agreeably with the terms of this assignment document.

WE HEREBY AUTHORIZE the Assignees to insert in this assignment document the filing date and application number of the application if the date and number are unavailable at the time this document is executed.

UPON SAID CONSIDERATION, we convey to the Assignees the right to make application in its own behalf for protection of the invention in the U.S. and countries foreign to the U.S. and to claim under the Patent Cooperation Treaty, the International Convention and/or other international arrangement for any such application the date of the U.S. application (or any other application on the invention) to gain priority with respect to other applications.

WE DO HEREBY COVENANT and agree with the Assignees that we will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that we will at any time upon request, without further or additional consideration, but at the expense of the Assignees, execute such additional assignments and

In re Appln. of Kang et al.
Attorney Docket No. P3059US

other writings and do such additional acts as the Assignees may deem necessary or desirable to perfect the Assignees' enjoyment of this assignment, and render all necessary assistance in making application for and obtaining original, continuation, continuation-in-part, divisional, reissued, reexamined, and National phase patents of the U.S. or of any and all foreign countries on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of all parties hereto.

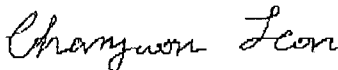
IN WITNESS WHEREOF, we have hereunder set our hands on the dates shown below.

Date 01/28/2009 _____

Bong-hyup KANG

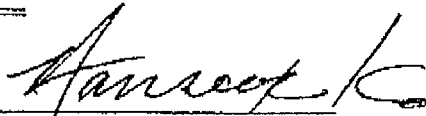
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Chang-won JEON

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Han-seok KO

Date _____ Witness _____

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